

AMENDMENTS TO THE CLAIMS

Please amend claim 1 as follows:

Claim 1 (Currently Amended) A two-layer laminated film for forming bumps, comprising:

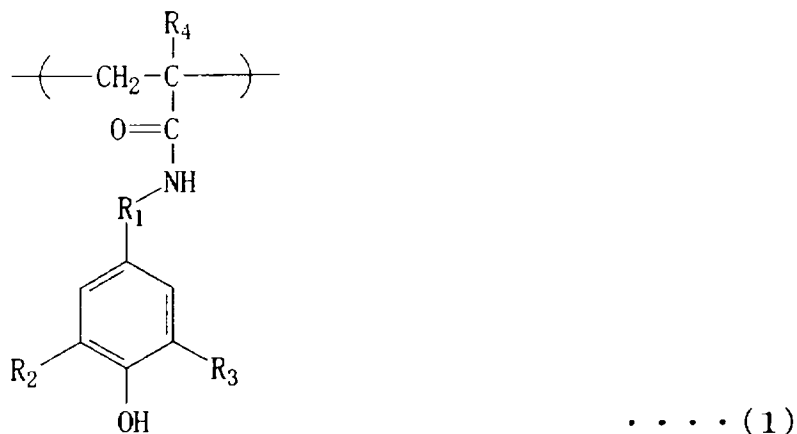
(I) a lower layer comprising a radiation-nonsensitive resin composition including a polymer

(A) and an organic solvent (B); and

(II) an upper layer comprising a negative radiation-sensitive resin composition;

the polymer (A) including a structural unit represented by Formula (1):

{~~Chem. 1~~}



wherein R₁ is $\text{---}(\text{CH}_2)_n\text{---}$ where n is an integer of 0 to 3, and R₂, R₃ and R₄ are the same or different from one another and are each a hydrogen atom or an alkyl group of 1 to 4 carbon atoms.

Claim 2 (Previously Presented) The two-layer laminated film for forming bumps according to claim 1, wherein the negative radiation-sensitive resin composition for the upper layer (II) includes a polymer having a carboxyl group and/or a phenolic hydroxyl group (C), a crosslinking agent (D), a radiation-activated radical polymerization initiator (E), and an organic solvent (F).

Claim 3 (Previously Presented) The two-layer laminated film for forming bumps according to claim 2, wherein the polymer (C) has a glass transition temperature (T_g) of not less than 40°C.

Claim 4 (Previously Presented) A transfer film comprising the laminated film claimed in claim 1 and a support film on which the laminated film is provided.

Claim 5 (Withdrawn) A process for forming bumps on electrode pads on a wiring board, comprising at least:

- (a) a step of providing the two-layer laminated film claimed in claim 1 on a substrate and forming a pattern of apertures at positions corresponding to electrode pads;
- (b) a step of introducing a low-melting metal in the apertures;
- (c) a step of reflowing the low-melting metal by heating to form bumps; and
- (d) a step of peeling and removing the two-layer laminated film from the substrate.

Claim 6 (Withdrawn) A process for forming bumps on electrode pads on a wiring board, comprising at least:

- (a) a step of providing the two-layer laminated film claimed in claim 1 on a substrate and forming a pattern of apertures at positions corresponding to electrode pads;
- (b) a step of introducing a low-melting metal in the apertures;
- (d') a step of peeling and removing the two-layer laminated film from the substrate; and
- (c') a step of reflowing the low-melting metal by heating to form bumps.